Hewlett Packard Enterprise

Product End-of-Life Disassembly Instructions

Product Category: Networking Equipment
Marketing Name / Model [List multiple models if applicable.]
HPE Altoline 6921 48XGT 6QSFP+ x86 ONIE AC Front-to-Back Switch (JL315A)
HPE Altoline 6921 48XGT 6QSFP+ x86 ONIE AC Back-to-Front Switch (JL316A)

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HPE products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	5
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0

Item Description	Notes	Quantity of items included in product
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Phillips screwdriver	various sizes
Small adjustable wrench	
Needle nose pliers	

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove the chassis lid
    1. Using a Phillips screwdriver, remove the screws (qty 20)
    2. Slide the lid off the chassis
2. Remove the two power supplies
    1. Locate the power supplies at either side of the back of the chassis
    2. While pressing the release lever toward the handle, pull the power supply out of the chassis
    3. Repeat for the other power supply
3. Remove the five fan assemblies from the back of the chassis
    1. Locate the fan assemblies in the middle of the back of the chassis
    2. Either by hand or using a Phillips screwdriver, loosen the set screw for each fan assembly
    3. Using the fan assembly handle, pull out a fan assembly
    4. Repeat for the remaining four fan assemblies
4. Remove the center PCA assembly
    1. Using a Phillips screwdriver, remove the two screws at the back corners of the center PCA assembly
    2. Using a small adjustable wrench, remove the two nuts at the front corners of the center PCA assembly
    3. Slowly remove the center PCA assembly from the chassis, taking into account the connector under the bottom left corner
5. Remove the two DIMMs from the center PCA assembly
    1. Gently spread the retaining levers away from the top DIMM
    2. Remove the top DIMM
    3. Repeat for the bottom DIMM
6. Remove the heatsink from the center PCA assembly
    1. Locate the heatsink fasteners on the underside of the PCA, opposite the heatsink
    2. Use needle nose pliers to pinch the heat sink fasteners while removing the heat sinks from the center PCA assembly
7. Remove the fan assembly PCA
    1. Disconnect the ribbon connector and the cable connector next to it from the fan assembly PCA
    2. Using a Phillips screwdriver, remove the four screws attaching the fan assembly PCA to the chassis
    3. Remove the fan assembly PCA from the chassis
8. Remove the main PCA
    1. Disconnect the ribbon connector and the cable connector that were attached to the fan assembly PCA
    2. Using a Phillips screwdriver, remove the two screws securing the small sheet metal air flow diverter to the middle of the main PCA

3. Remove the small sheet metal air flow diverter
4. Using a Phillips screwdriver, remove the two screws securing the double bend sheet metal air flow diverter to the left side of the main PCA
5. Remove the double bend sheet metal air flow diverter
6. Using a small adjustable wrench, remove the four hexagonal studs near the corners of the heat sink
7. Using a small adjustable wrench, remove the two small hexagonal studs that were supporting the front edge of the middle PCA stack
8. Using a Phillips screwdriver, remove the two screws located on the bottom of the chassis securing a close out plate
9. Remove the close out plate
10. Using a Phillips screwdriver, remove the screws securing the two power supply connectors (two screws each)
11. Repeat for the other power supply connector
12. Using a Phillips screwdriver, remove the nine screws holding down the main PCA
13. Remove the main PCA from the chassis

9. Using a Phillips screwdriver, loosen the screws securing the three heat sinks (four screws each) to the main PCA
10. Remove the heat sinks and their backing hardware from the main PCA

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).